



# SOT1443-2

wafer level chip-scale package; 30 bumps; 2.26 x 2.56 x 0.51 mm (backside coating included)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP30
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-6-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.53	-	2.56	2.59	mm
E	package width	2.23	-	2.26	2.29	mm
A	seated height	0.47	-	0.51	0.55	mm
A <sub>2</sub>	package height	0.29	-	0.31	0.34	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	30	-	





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### 3. Legal information

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